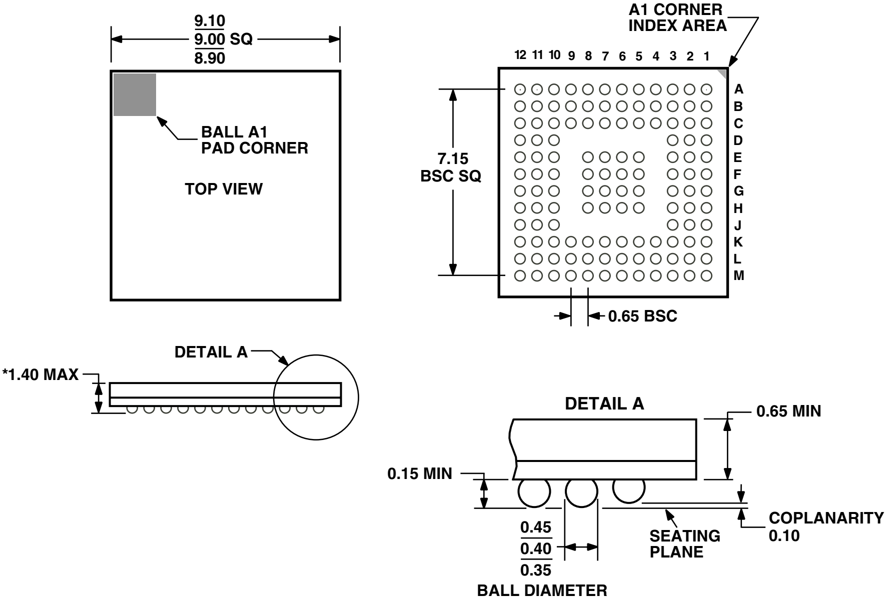
124-Lead Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-124-1)

Dimensions shown in millimeters



*COMPLIANT TO JEDEC STANDARDS MO-225
WITH THE EXCEPTION OF PACKAGE HEIGHT.